



**Minutes of P-2.2 Subcommittee Meeting
Paper, Film, Mica & Wet-Electrolytic Capacitors**

Wednesday October 7, 2009,
Doubletree Hotel, 411 West Bay Street, Savannah, GA 31401, (912) 790-7000

1.0 Call to Order - Circulate Membership Roster

1.1 Meeting called to order at 8:10 AM by Chairman Laird Macomber

2.0 Committee Organization and Procedures

2.1 Membership Introductions were conducted and Roster circulated.

A quorum was present. The attendance was as follows:

NAME	COMPANY
Chris Reynolds [via telephone]	AVX
Laird Macomber	CDE
Michael Lauri [via telephone]	IBM
Mary Carter Berrios [via telephone]	KEMET
Jayson Young	KEMET
Ted Coler	Vishay

Member Organizations Present	Present at Fall 2009 Meeting	Present at Spring 2009 Meeting	Present at Fall 2008 Meeting
AVX	Y	Y	N
CDE	Y	Y	Y
IBM	Y	Y	Y
KEMET	Y	Y	Y
Vishay	Y	N	Y

Member Organizations Absent	Other Organizations Present
none	none

2.2 Approval of Agenda: Approved

2.3 Approval of April 29, 2009, P-2.2 Subcommittee Meeting Minutes: Approved

2.4 Correspondence: No correspondence had been received.

2.5 Review of Committee's Scope: Paper, film, mica and wet-electrolytic capacitors for all applications, except those for inductive heating and utility power-factor correction.

3.0 Reports: No reports had been received.

4.0 Old business

4.1 Status PN 5182 Fixed Film Dielectric Capacitors Stacked Metallized Chip Capacitors, the SMT film cap specification: This new standard is to be sent to EIA for issuance as a Standard Proposal for 60-day ballot when complete. The draft includes PET and PPS dielectrics and will follow the format of the ceramic capacitors and include references to IEC 60384-1, -19, -20 and -23. Because case sizes are not standardized, the standard will include only a range of sizes for the capacitance values for the E6 preferred-values series with case-size ranges for each dielectric, but without land patterns because there is too much variation among makers. Marking would be optional with EIA marking recommended. Tolerances would be per EIA.

These tests would be included:

- Qualification 2000 hour life test
- Charge/discharge 10,000 cycles
- Temperature cycling
- Resistance to solder heat
- Solderability
- Humidity
- Electrical test for cap, DF and IR

And include requirements for sample size, test conditions and acceptance criteria.

Chairman Laird agreed to arrange for a working-group meeting in January 2010.

4.2 Five-year review of documents: It was planned to review website list of projects and specifications. Ed Mikoski has told Chairman Laird that he is updating the list.

5.0 New Business

5.1 New standard for medium-power film capacitors: At the Fall 2008 summit Chris Reynolds said that he would look at IEC test conditions for use with medium power film capacitors and would provide a list of companies for possible standard offering. Following this meeting Chairman Laird has had PN-5206 assigned for this new standard. It will issued as EIA968.

6.0 Next Meeting: It will be in Orlando, FL in March 2010 or later.

7.0 Adjournment: Meeting was adjourned at 9:30 AM



Laird L Macomber
Chairman

Michael Lauri
Acting Secretary

